PI3USB302-A

3.3V, USB 3.0, 1-Port, 2:1 Mux/DeMux Switch

Features

➔ 2 Differential Channel, 2:1 Mux/DeMux

➔ USB 3.0 SuperSpeed switch

➔ Bi-directional operation

➔ Low Bit-to-Bit Skew, 10 ps max

➔ 3dB Bandwidth = 8.1GHz

➔ Low channel-to-channel skew: 20 ps max

➔ Low insertion loss: -1dB @ 2.5 GHz (5.0 Gbps)

➔ Low Crosstalk: -33dB @ 2.5 GHz (5.0 Gbps)

➔ Low Off Isolation: -27dB @ 2.5 GHz (5.0 Gbps)

➔ Low Return Loss: -23.3dB @ 2.5GHz (5.0Gbps)

➔ V_{DD} Operating Range: 3.3 V +/-10%

➔ ESD Tolerance: 2 kV HBM

➔ Low current: 0.2mA Typ.

➔ Packaging (Pb-free & Green):

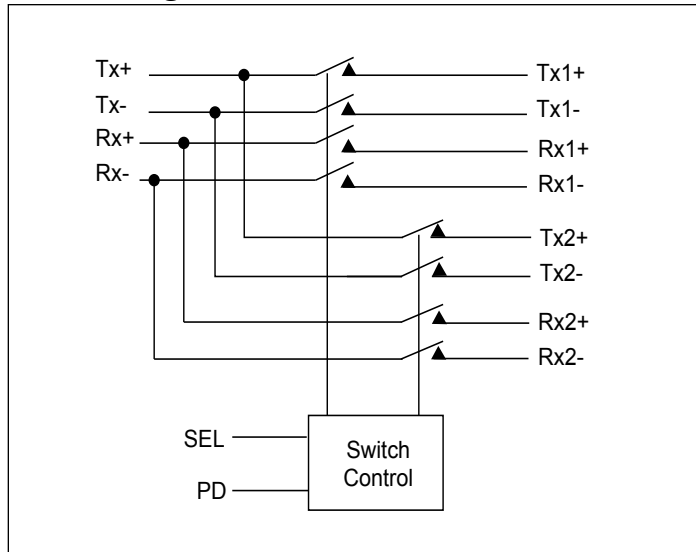 ▫ – 20-contact TQFN (2.5 × 4.5mm)

Description

Pericom Semiconductor's PI3USB302-A is a 2-differential channel bi-directional multiplexer/demultiplexer switch. Due to its low bit-to-bit skew, high channel-to-channel noise isolation and bandwidth, this product is ideal for USB 3.0 signal switching at 5.0 Gbps.
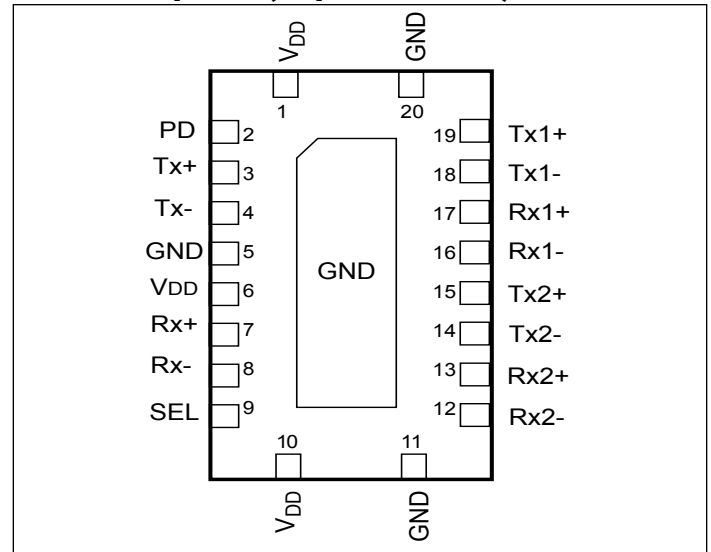
Application

Routing USB 3.0 SuperSpeed signals

Block Diagram

Pin Description (Top-side view)

Truth Table

Function	SEL	PD
port 1 is active	L	L
port 2 is active	H	L
Both Ports Hi-z, IC power down	x	H

Pin Description

Pin #	Pin Name	I/O	Description
2	PD	I	Power Down input. see truth table on page 1 for functionality
3	Tx+	I/O	Signal I/O, Transmit differential pair from common port
4	Tx-	I/O	
7	Rx+	I/O	Signal I/O, Receive differential pair from common port
8	Rx-		
9	SEL	I	Operation mode Select (when SEL=0: port 1 is active, when SEL=1: port 2 is active
14	Tx2-	I/O	Signal I/O, Transmit differential pair, port 2
15	Tx2+		
12	Rx2-	I/O	Signal I/O, Receive differential pair, port 2
13	Rx2+	I/O	
17	Rx1+	I/O	Signal I/O, Receive differential pair, port 1
16	Rx1-		
19	Tx1+	I/O	Signal I/O, Transmit differential pair, port 1
18	Tx1-		
6, 10, 1	V$_{DD}$	Pwr	3.3V ±10% Positive Supply Voltage
5, 11, 20, center pad	GND	Pwr	Power ground

Maximum Ratings

(Above which useful life may be impaired. For user guidelines, not tested.)

Storage Temperature ....−65°C to +150°C
Supply Voltage to Ground Potential ....−0.5V to +4.6V
Channel DC Input Voltage ....−0.5V to 1.5V
SEL/PD DC Input Voltage ....−0.5V to 4.6V
DC Output Current 120mA
Power Dissipation 0.5W

Note: Stresses greater than those listed under MAXI-MUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Electrical Characteristics

Recommended Operating Conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V_{DD}	3.3V Power Supply		3.0	3.3	3.6	V
I_{DD}	Total current from V_{DD} 3.3V supply	SEL = 0V or V_{DD},		0.2	1	mA
I_{DD_PD}	Power down current	PD = 1		20	40	uA
T_{CASE}	Case temperature range for operation within spec.		-40		85	Celsius

DC Electrical Characteristics for Switching over Operating Range

Parameters	Description	Test Conditions[1]	Min	Typ[1]	Max	Units
$V_{IH-SEL, PD}$	Input HIGH Voltage, SEL, PD Input		2		3.6	V
$V_{IL-SEL, PD}$	Input LOW Voltage, SEL, PD Input		0		0.8	
V_{IK}	Clamp Diode Voltage	V_{DD} = Max, I_{IN} = −18mA		−0.7	−1.2	
I_{IH}	Input HIGH Current SEL, PD Input	V_{DD} = Max, V_{IN} = V_{DD}	-5		+5	μA
I_{IL}	Input LOW Current, SEL, PD Input	V_{DD} = Max, V_{IN} = 0V	-5		+5	
I_{IH}	Input High Current, T_X, R_X	V_{DD} = Max, V_{IN} = 1.5V	-10		+10	
I_{IL}	Input LOW Current, T_X, R_X	V_{DD} = Max, V_{IN} = 0V	-10		+10	
I_{OZH}	High Z HIGH Current, T_X, R_X	V_{DD} = Max, V_{IN} = 1.5V	-10		+10	μA
I_{OZL}	High Z LOW Current, T_X, R_X	V_{DD} = Max, V_{IN} = 0V	-10		+10	μA

Note:
1. Typical values are at V_{DD} = 3.3V, T_A = 25°C ambient and maximum loading.

Switching Characteristics

Parameters	Description	Test Conditions	Min.	Typ.	Max.	Units
t_{PZH}, t_{PZL}	Line Enable Time			25	30	ns
t_{PHZ}, t_{PLZ}	Line Disable Time			5	25	
t_{b-b}	Bit-to-bit skew within the same differential pair			5	10	ps
t_{ch-ch}	Channel-to-channel skew				20	

Dynamic Electrical Characteristics

Parameter	Description	Test Conditions	Min.	Typ.[1]	Max.	Units
DDIL[2,3]	Differential Insertion Loss (V_{IN} = -10dBm, DC = 0V)	f= 100MHz		-0.4		dB
		f = 1.25GHz		-0.6		
		f = 2.5GHz		-1.0		
		f=4.0GHz		-1.7		
DDIL$_{OFF}$[2,3]	Differential Off Isolation	f= 100MHz		-59		dB
		f = 1.25GHz		-37		
		f = 2.5GHz		-27		
		f=4.0GHz		-21		
DDRL[2]	Differential Return Loss	f= 100MHz		-27		dB
		f = 1.25GHz		-23.3		
		f = 2.5GHz		-23.3		
		f=4.0GHz		-13.5		
DDNEXT[2,3]	Near End Crosstalk	f= 100MHz		-57		dB
		f = 1.25GHz		-38		
		f = 2.5GHz		-33		
		f=4.0GHz		-32		
BW	-3dB Bandwidth			8.1		GHz

Notes:

1.Guaranteed by design. Typical values are at V_{DD} = 3.3V , T_A = 25°C ambient and maximum loading.

2. S parameters are measured with our evaluation board made with Rogers (R04350) material. Trace width is 30 mil, length 540 mil, trace impedence is 50 Ohm (+/- 5%) and total insertion loss of the trace is 0.5dB@4GHz.

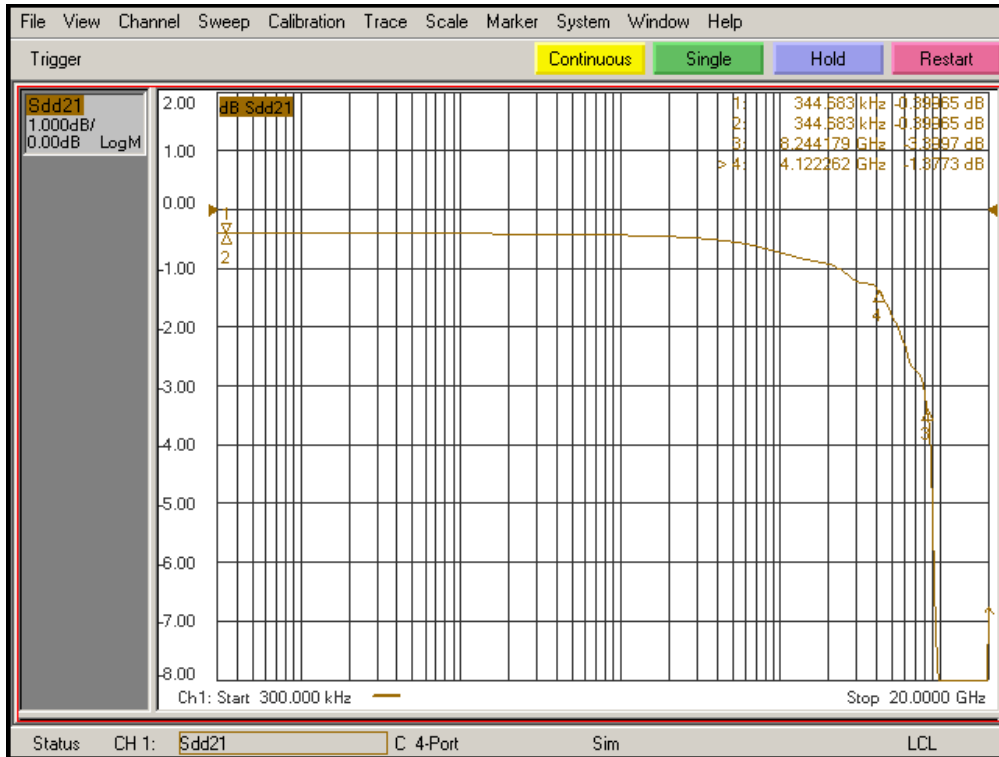3. Measurement done with fixture deembedding.
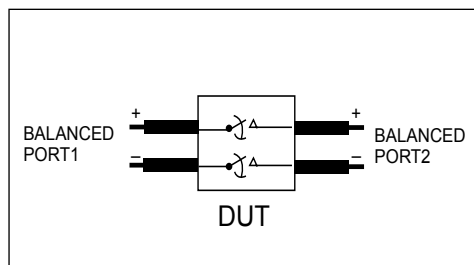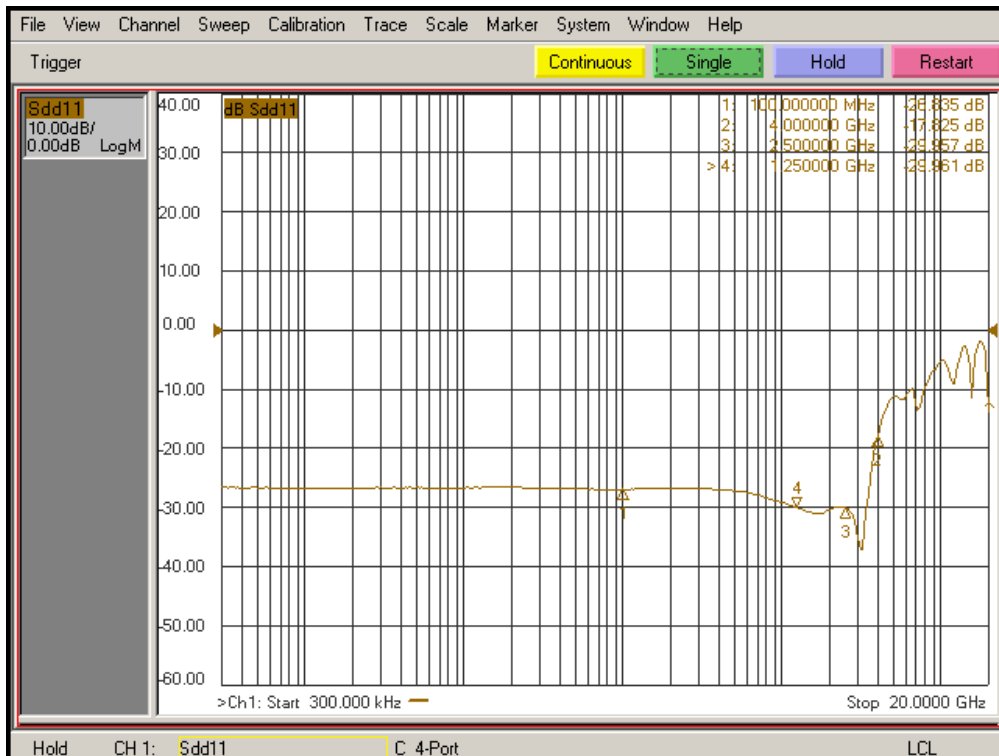

Diff. Insertion Loss and Return Test Circuit
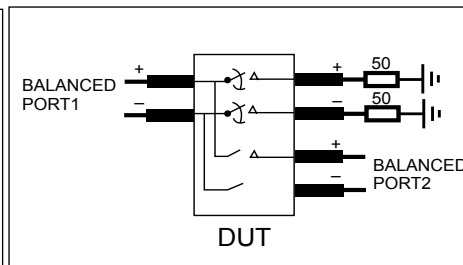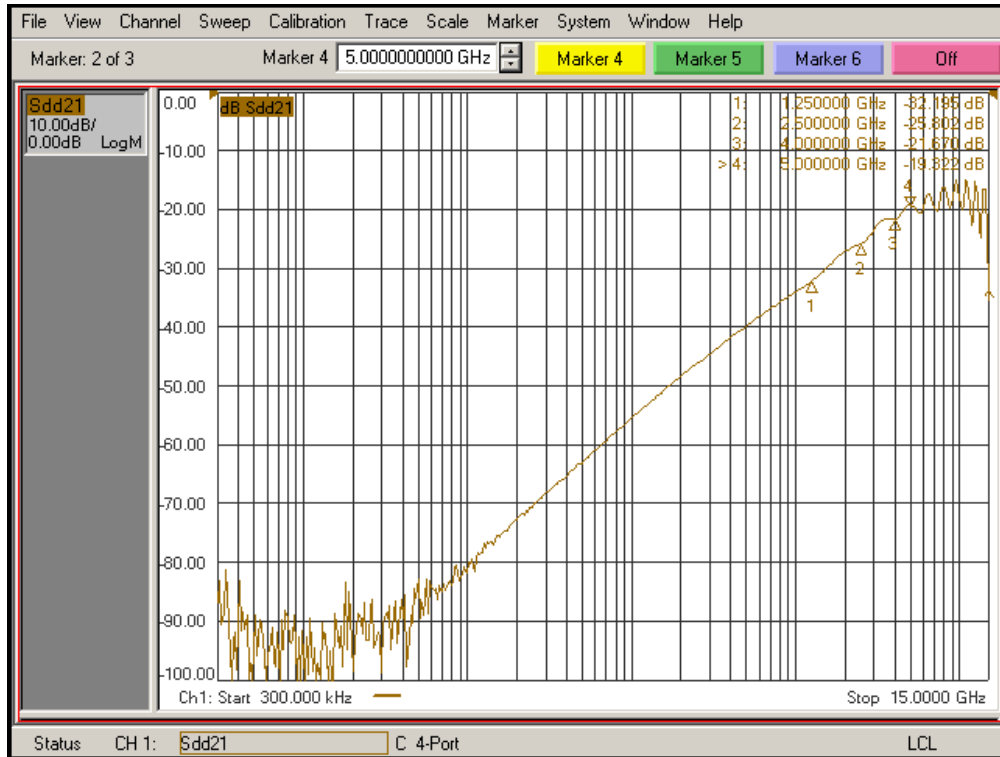

Diff. Off Isolation Test Circuit
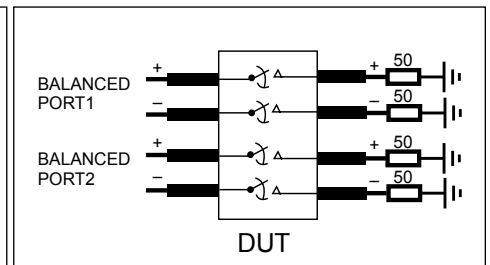
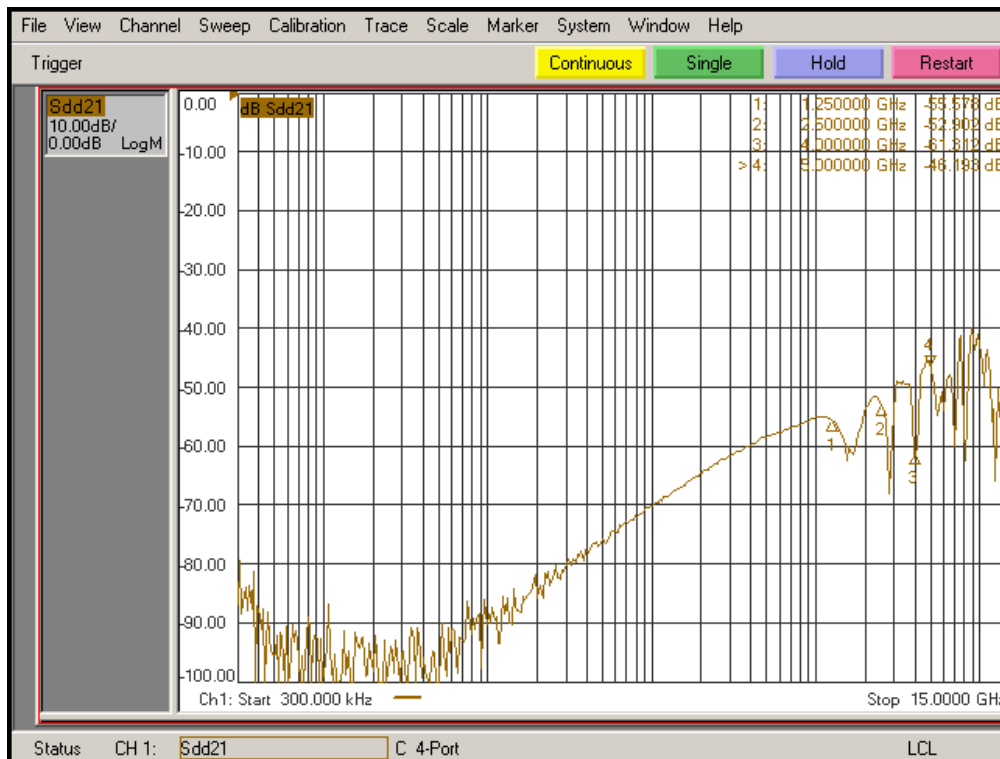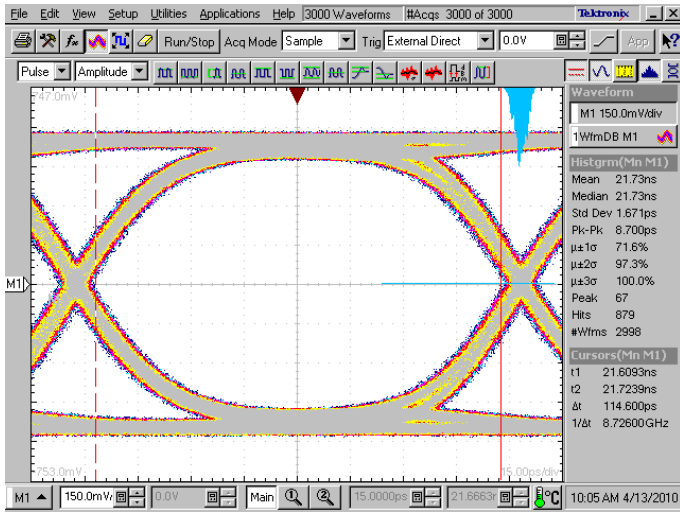**Diff. Near End Xtalk Test Circuit**

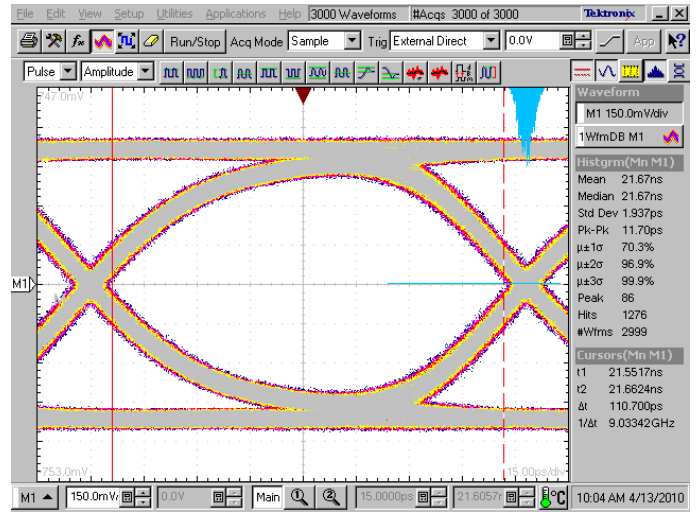**Differential Insertion Loss**

Differential Return Loss

Differential Off Isolation

Differential Crosstalk

5.0 Gbps RX signal eye without PI3USB302-A

5.0 Gbps RX signal eye with PI3USB302-A

PERICOM®

Test Circuit for Electrical Characteristics[1-5]
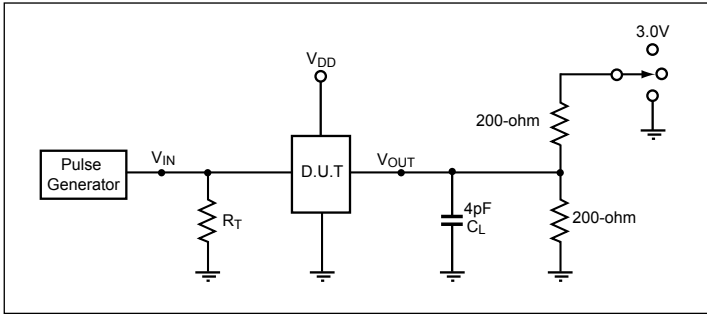
Switch Positions

Test	Switch
t_{PLZ}, t_{PZL}	3.0V
t_{PHZ}, t_{PZH}	GND
Prop Delay	Open

Switching Waveforms
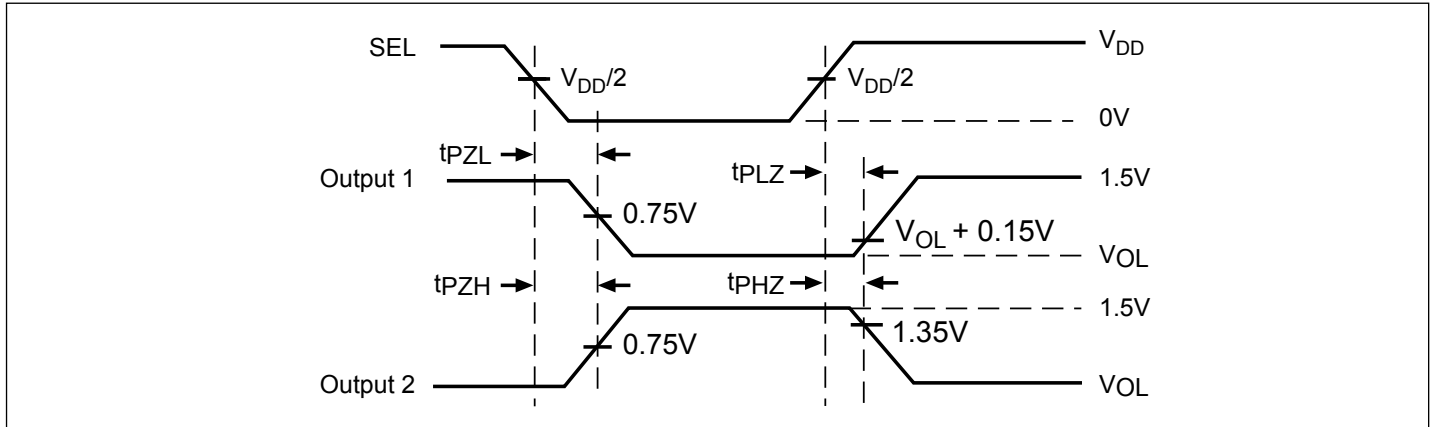
Voltage Waveforms Enable and Disable Times

Packaging Mechanical: 20-TQFN (ZB)

SYMBOLS	MIN.	NOM.	MAX.
A	--	--	1.00
A1	0.00	0.02	0.05
A3	0.20 REF.		
b	0.18	0.25	0.30
D	2.40	2.50	2.60
E	4.40	4.50	4.60
e	0.50 BSC		
L	0.30	0.40	0.50
K	0.20	—	—
D2	0.90	1.00	1.10
E2	2.90	3.00	3.10

RECOMMENDED STENCIL DESIGN for EPAD
(0.125mm THICK STENCIL)

RECOMMENDED LAND PATTERN

TOP VIEW

BOTTOM VIEW

PIN1 INDEX AREA

PERICOM
Enabling Serial Connectivity

DATE: 10/20/14

DESCRIPTION: 20-Contact, Very Thin Quad Flat No-Lead (TQFN)

PACKAGE CODE: ZB (ZB20)

DOCUMENT CONTROL #: PD-2104

REVISION: B

NOTE :
1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO-241
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY.
5. THERMAL PAD SOLDERING AREA (MESH STENCIL DESIGN IS RECOMMENDED).

14-0265

Note:

1. For latest package info, please check: http://www.pericom.com/products/packaging/mechanicals.php

Ordering Information

Ordering Code	Package Code	Package Type
PI3USB302-AZBE	ZB	20-Contactm Very Think Quad Flat No-Lead (TQFN)
PI3USB302-AZBEX	ZB	20-Contactm Very Think Quad Flat No-Lead (TQFN), Tape & Reel

Notes:
• Thermal characteristics can be found on the company web site at www.pericom.com/packaging/
• E = Pb-free and Green
• Adding an X suffix = Tape/Reel

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单击下面可查看定价，库存，交付和生命周期等信息

>>Diodes Incorporated(达迩科技（美台）)